Qualcomm

RF360
Europe GmbH

Sample data sheet

BAW filter
6.5 GHz Wi-Fi 6E UNII5-8

Project: AS83C

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Table of contents

1 Application

- Low-loss BAW RF coexistence filter for 6.5GHz Wi-Fi 6 UNII5-8
- WiFi 6E UNII5-8: 6535 MHz (pass band 1180 MHz)
- Usable pass band : 1180 MHz

2 Features

- Package size $1.8_{\pm 0.05}$ mm × $1.4_{\pm 0.05}$ mm
- Package height 0.65 mm (max.)
- Approximate weight 1 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

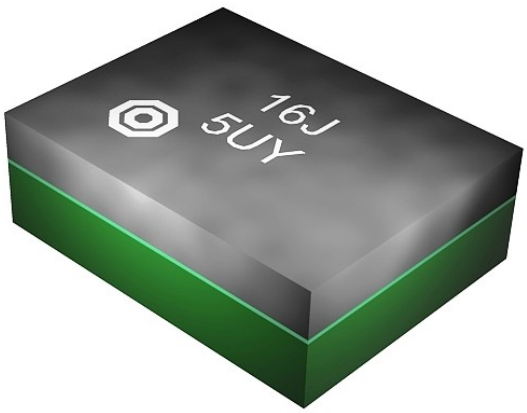

Figure 1: Picture of component with example of product marking.

3 Package

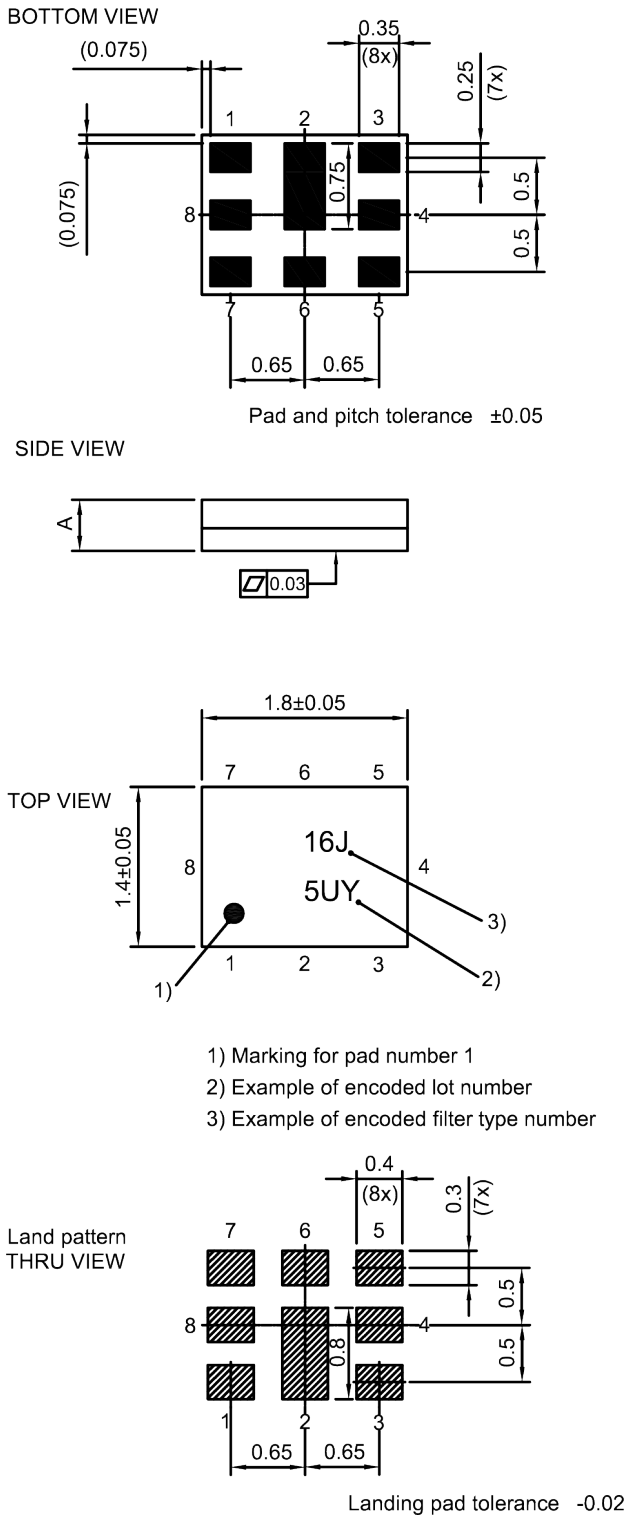

Figure 2: Drawing of package with package height A = 0.65 mm (max.). See Sec. Package information (p. 19).

4 Pin configuration

- 3 Output
- 7 Input
- 1, 2, 4, 5, 6, 8 Ground

5 Matching circuit

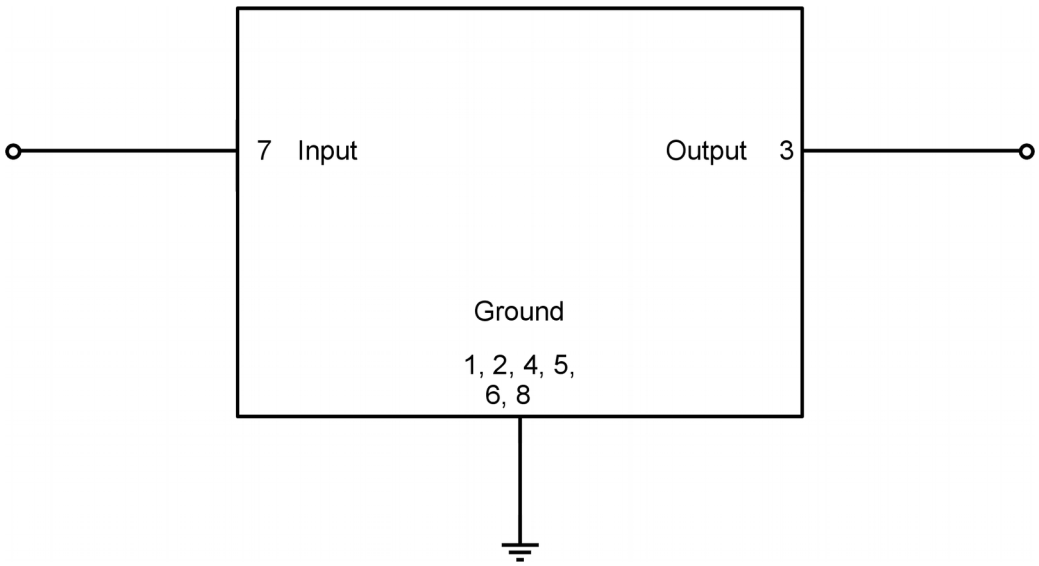

Figure 3: Schematic of matching circuit. No external matching components required.

6 Characteristics

Temperature range for specification T_{SPEC} = −40 °C ... +85 °C
Input terminating impedance Z_{IN} = 50 Ω
Output terminating impedance Z_{OUT} = 50 Ω

				Development status[1]			DGL[2]		
Characteristics				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	**min.**	**max.**	
Maximum insertion attenuation			α_{max}						
	5945 ... 6015	MHz		—	3.6	—	—	3.0	dB
	6105 ... 7125	MHz		—	2.4	—	—	3.0	dB
Amplitude ripple (p-p)			$\Delta\alpha$						
	5945 ... 7125	MHz		—	1.7	—	—	1.5	dB
Maximum VSWR			$VSWR_{max}$						
@ input port	5945 ... 5985	MHz		—	2.0	—	—	2.0	
	5985 ... 7125	MHz		—	1.3	—	—	2.0	
@ output port	5945 ... 5985	MHz		—	1.6	—	—	2.0	
	5985 ... 7125	MHz		—	1.6	—	—	2.0	
Attenuation			α_{min}						
	10 ... 2500	MHz		—	43	—	40	—	dB
	2400 ... 2570	MHz		—	44	—	30	—	dB
	2570 ... 3400	MHz		—	42	—	30	—	dB
	3400 ... 3870	MHz		—	42	—	25	—	dB
	3870 ... 4400	MHz		—	43	—	15	—	dB
	4400 ... 5170	MHz		—	46	—	30	—	dB
	5170 ... 5825	MHz		—	43	—	40	—	dB
	5825 ... 5895	MHz		—	13	—	35	—	dB
	11870 ... 14250	MHz		—	41	—	35	—	dB
	17805 ... 20000	MHz		—	40	—	35	—	dB
Wi-Fi 6 80MHz			α_{WLAN}[3]						
	5170 ... 5350	MHz		—	50	—	40	—	dB
	5170 ... 5825	MHz		—	44	—	40	—	dB
	5170 ... 5895	MHz		—	21	—	40	—	dB
	5490 ... 5825	MHz		—	44	—	40	—	dB
Wi-Fi 6 160MHz			α_{WLAN}[4]						
	5170 ... 5350	MHz		—	51	—	40	—	dB
	5170 ... 5825	MHz		—	46	—	40	—	dB
	5170 ... 5895	MHz		—	24	—	40	—	dB
	5490 ... 5835	MHz		—	45	—	40	—	dB

1) Values in columns min., typ., and max. indicate the development status of the current version.
2) Values in column design goal (DGL) indicate the target performance.
3) Average over each WLAN channel with band width of 80 MHz.
4) Average over each WLAN channel with band width of 160 MHz.

7 Maximum ratings

Operable temperature	T_{OP} = −40 °C ... +95 °C	
Storage temperature	T_{STG} [1] = −40 °C ... +95 °C	
DC voltage	$\|V_{DC}\|$ [2] = 0 V (max.)	
ESD voltage		
	V_{ESD} [3] = 50 V (max.)	Human body model.
	V_{ESD} [4] = 100 V (max.)	Machine model.
Input power	P_{IN}	
@ input port: 5945 ... 7125 MHz	28 dBm[6]	ON-state power of 160 MHz Wi-Fi downlink signal with 70% duty cycle for t.b.d. h @ 55 °C. Source and load impedance 50Ω.[5]
@ input port: other frequency ranges	10 dBm	Continuous wave for 10000 h @ 55 °C. Source and load impedance 50Ω.

1) Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.
2) In case of applied DC voltage blocking capacitors are mandatory.
3) According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.
4) According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.
5) Expected lifetime according to accelerated power durability simulation, and wear out models.
6) Hardware test to be done, target=28dBm.

8 Transmission coefficient

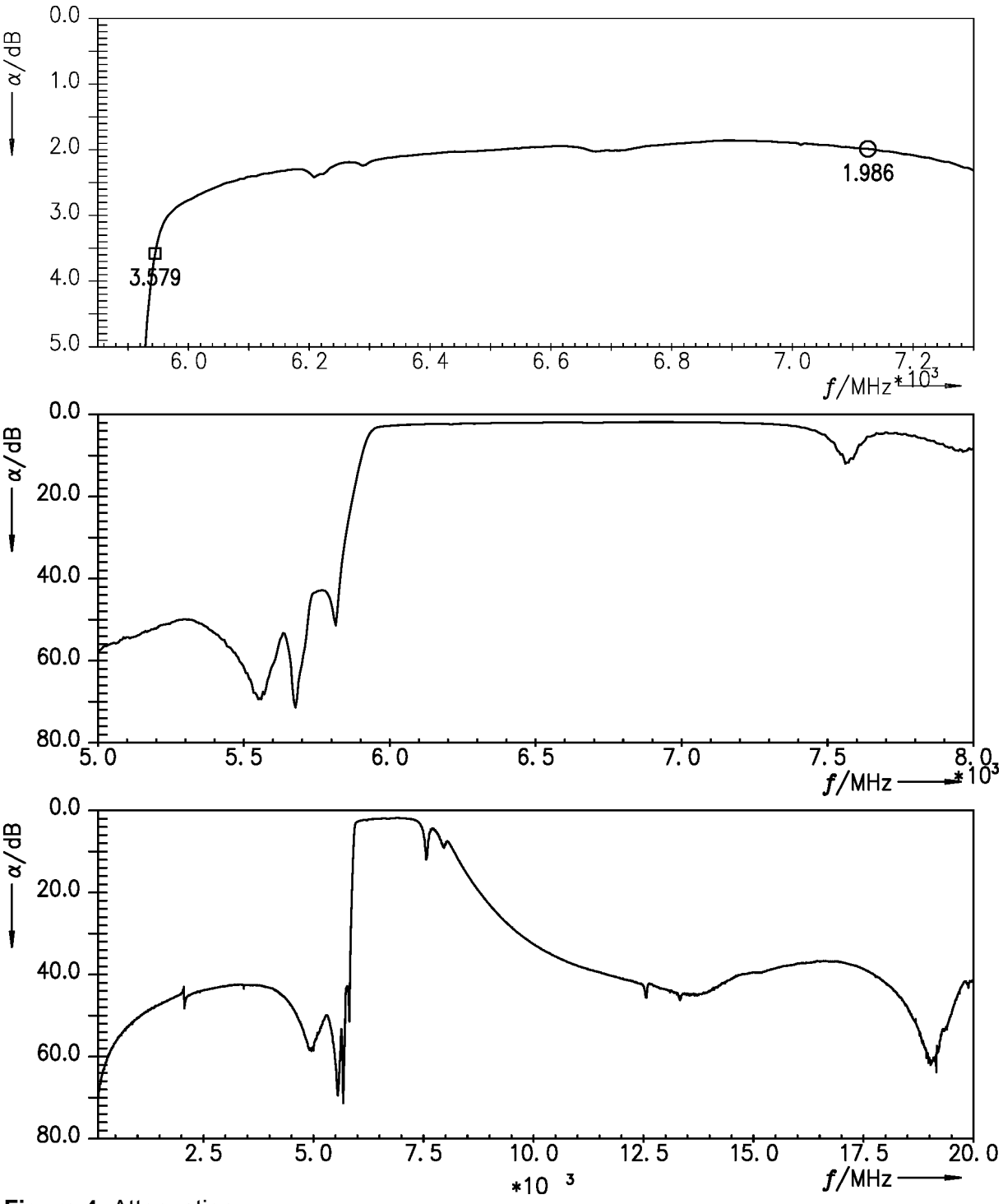

Figure 4: Attenuation.

9 Transmission coefficient (WLAN)

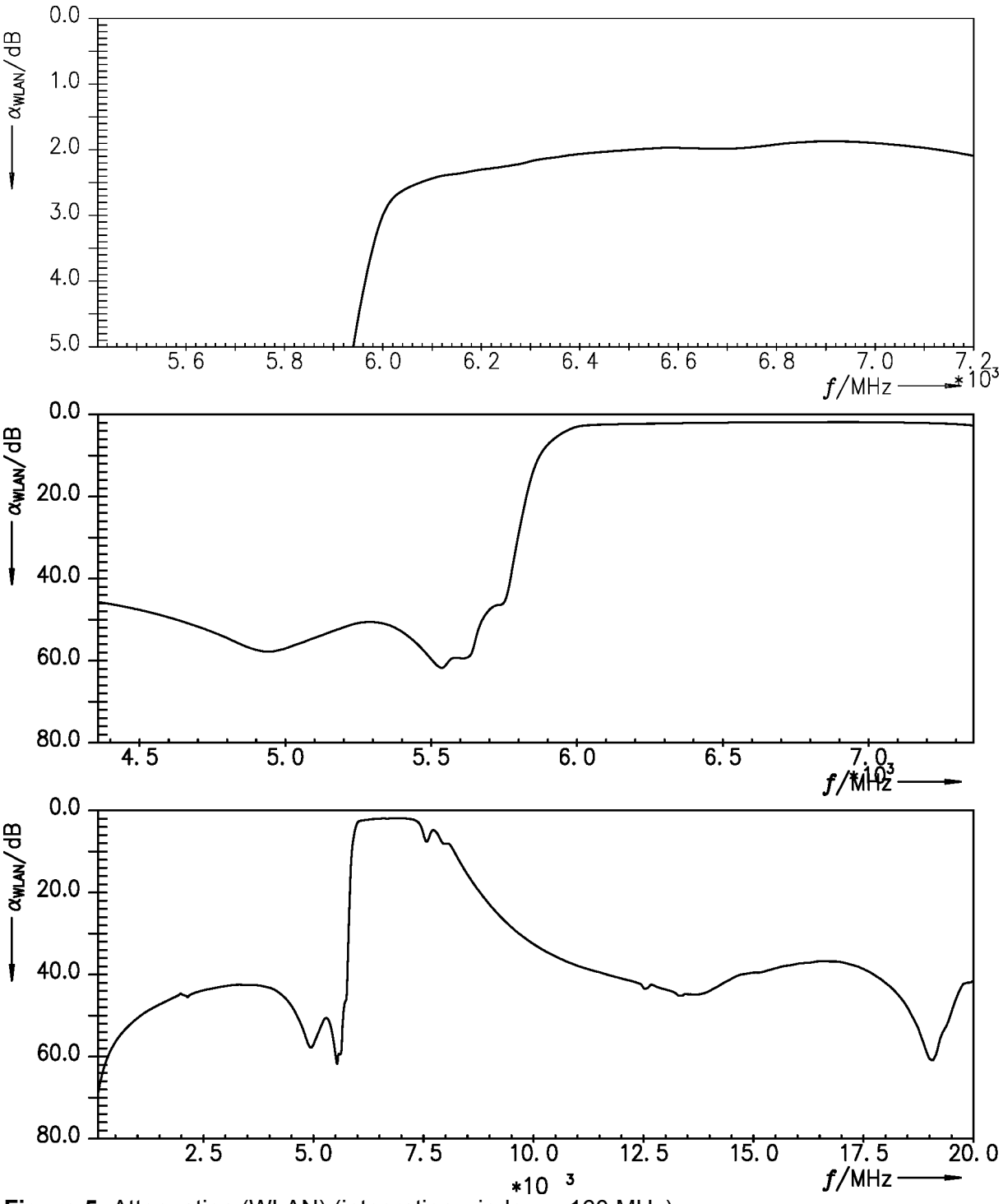

Figure 5: Attenuation (WLAN) (integration window = 160 MHz).

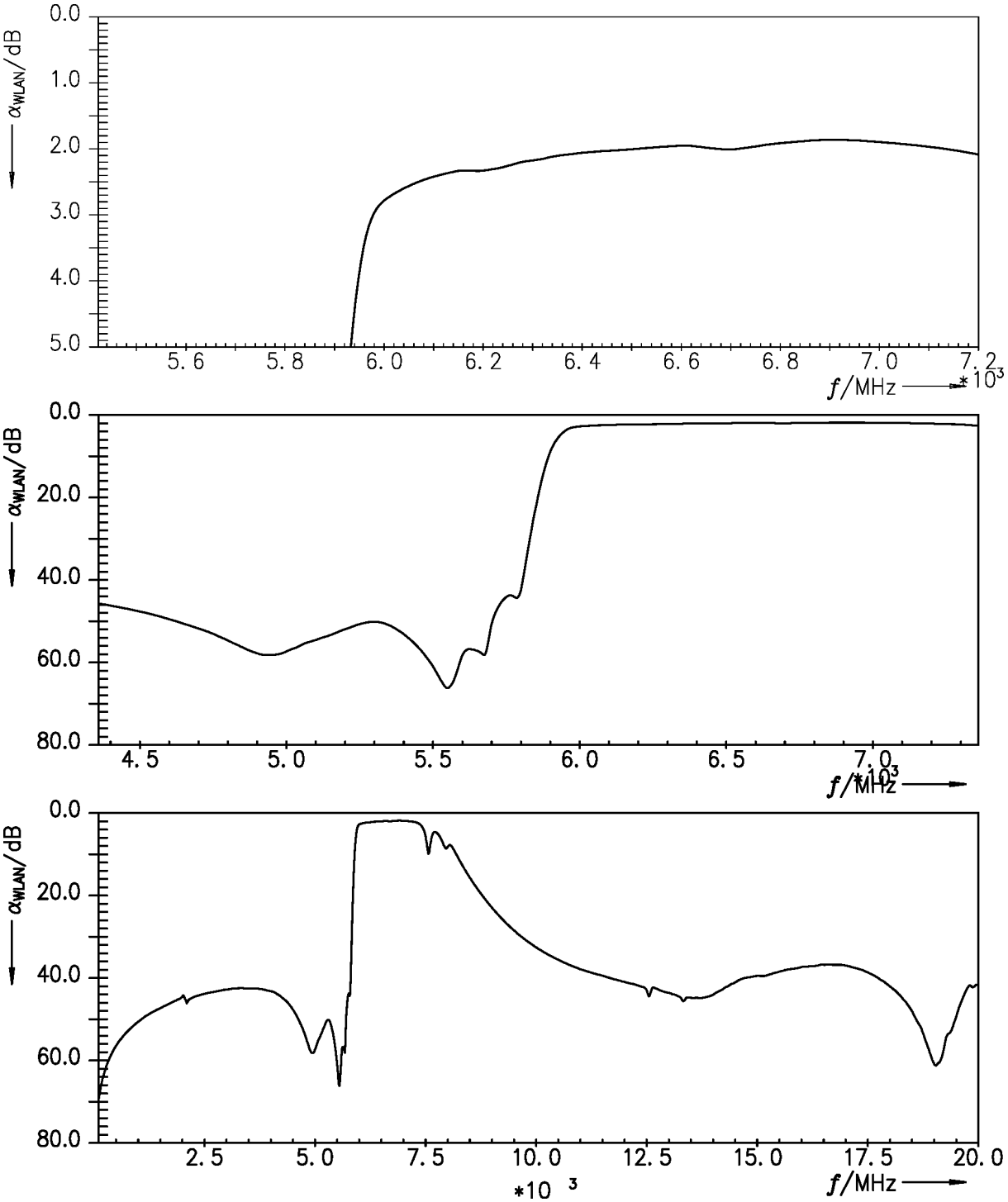

Figure 6: Attenuation (WLAN) (integration window = 80 MHz).

10 Reflection coefficients

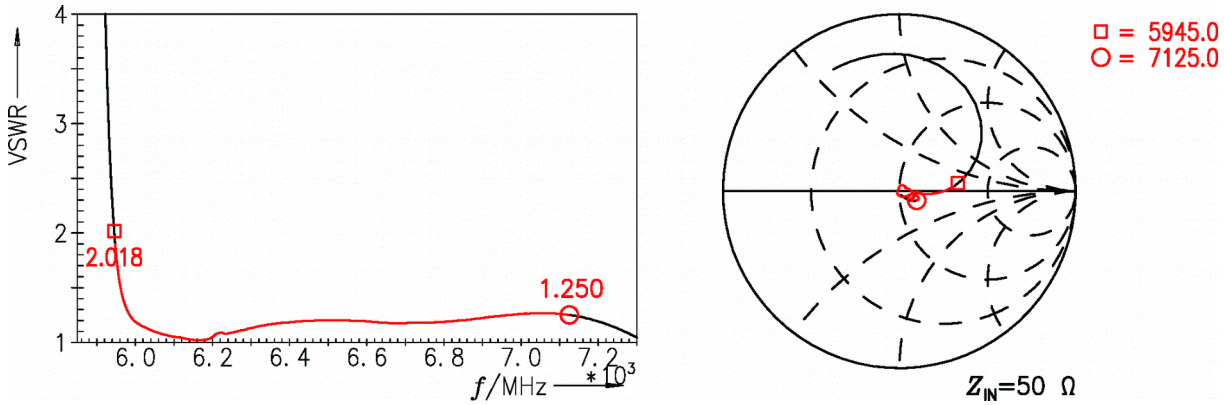

Figure 7: Reflection coefficient at input port.

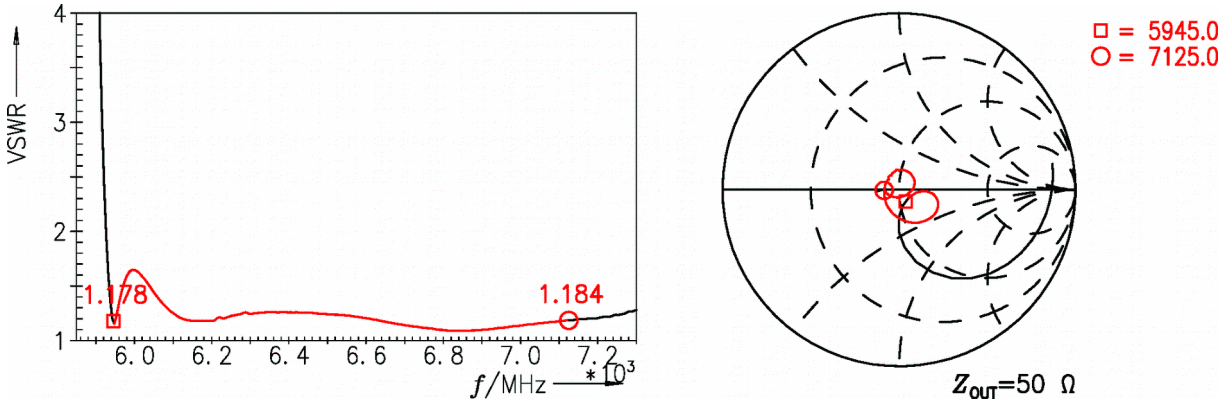

Figure 8: Reflection coefficient at output port.

11 Packing material

11.1 Tape

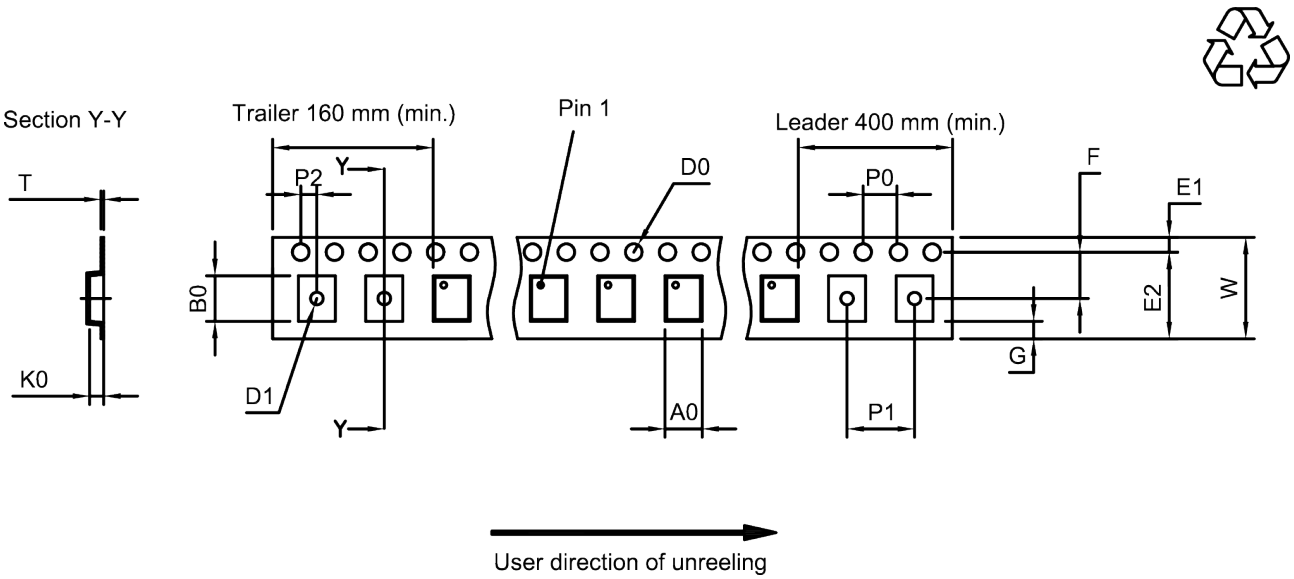

Figure 9: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A_0	$1.6_{\pm 0.05}$ mm
B_0	$2.0_{\pm 0.05}$ mm
D_0	$1.5^{+0.1/-0}$ mm
D_1	$0.8^{+0.1/-0}$ mm
E_1	$1.75_{\pm 0.1}$ mm

E_2	6.25 mm (min.)
F	$3.5_{\pm 0.05}$ mm
G	0.75 mm (min.)
K_0	$0.8_{\pm 0.05}$ mm
P_0	$4.0_{\pm 0.1}$ mm

P_1	$4.0_{\pm 0.1}$ mm
P_2	$2.0_{\pm 0.05}$ mm
T	$0.25_{\pm 0.03}$ mm
W	$8.0^{+0.3/-0.1}$ mm

Table 1: Tape dimensions.

11.2 Reel with diameter of 180 mm

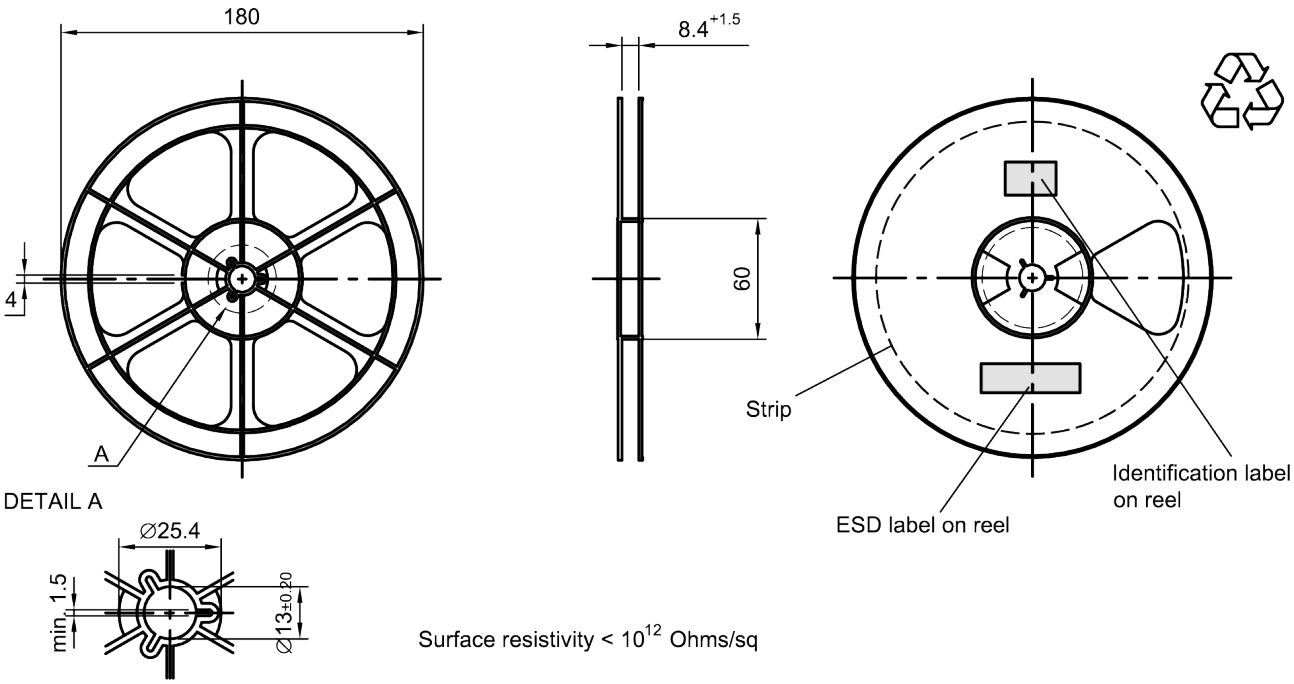

Figure 10: Drawing of reel (first-angle projection) with diameter of 180 mm.

Dimensions [mm]
X = 220+5
Y = 235+5
Sealing area 10±3

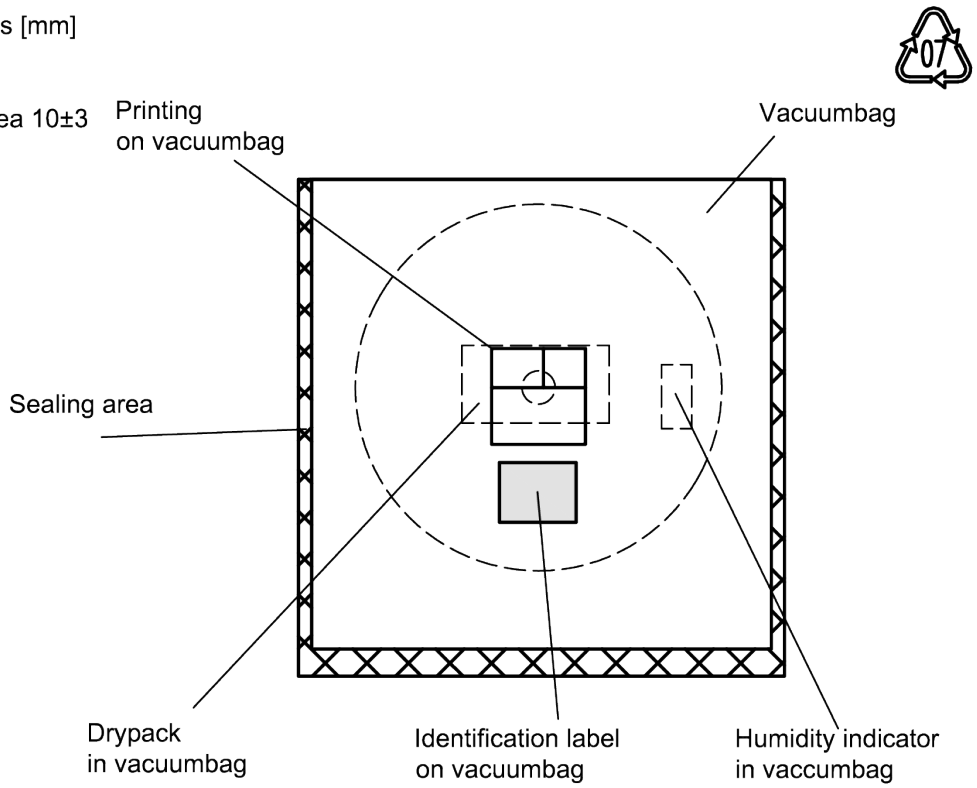

Figure 11: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

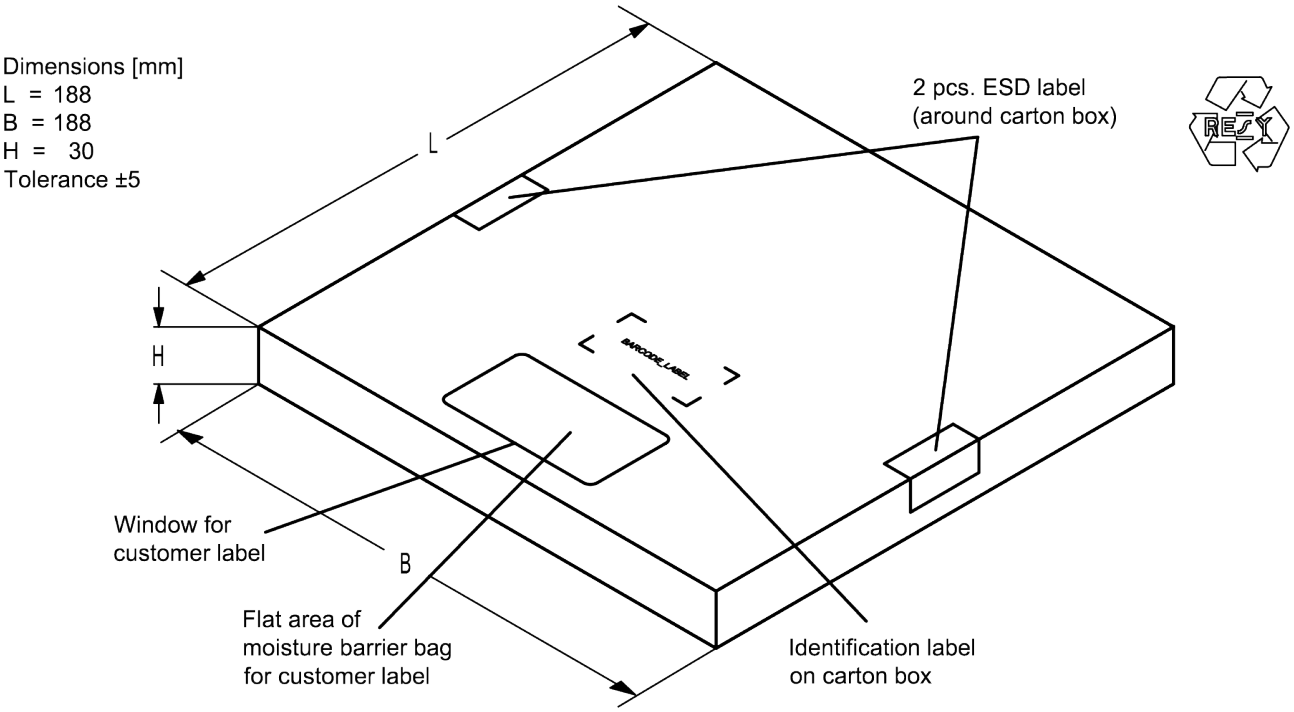

Figure 12: Drawing of folding box for reel with diameter of 180 mm.

11.3 Reel with diameter of 330 mm

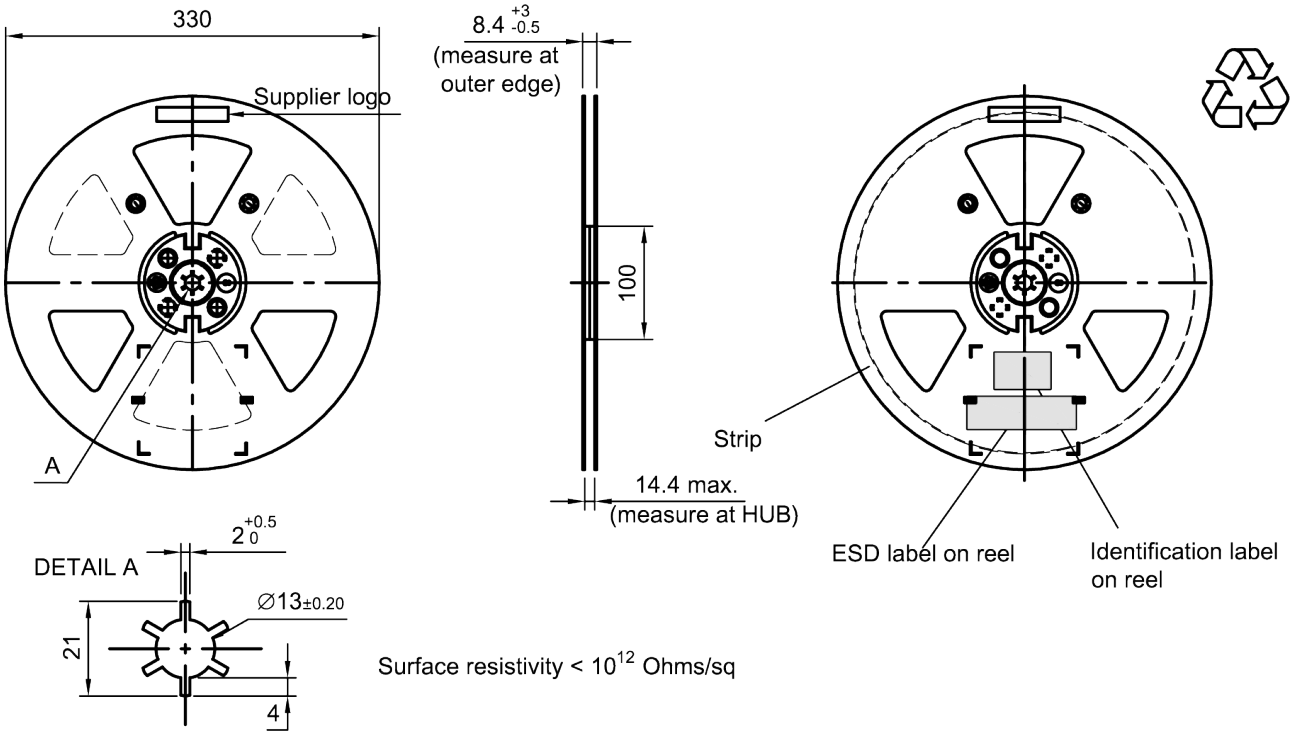

Figure 13: Drawing of reel (first-angle projection) with diameter of 330 mm.

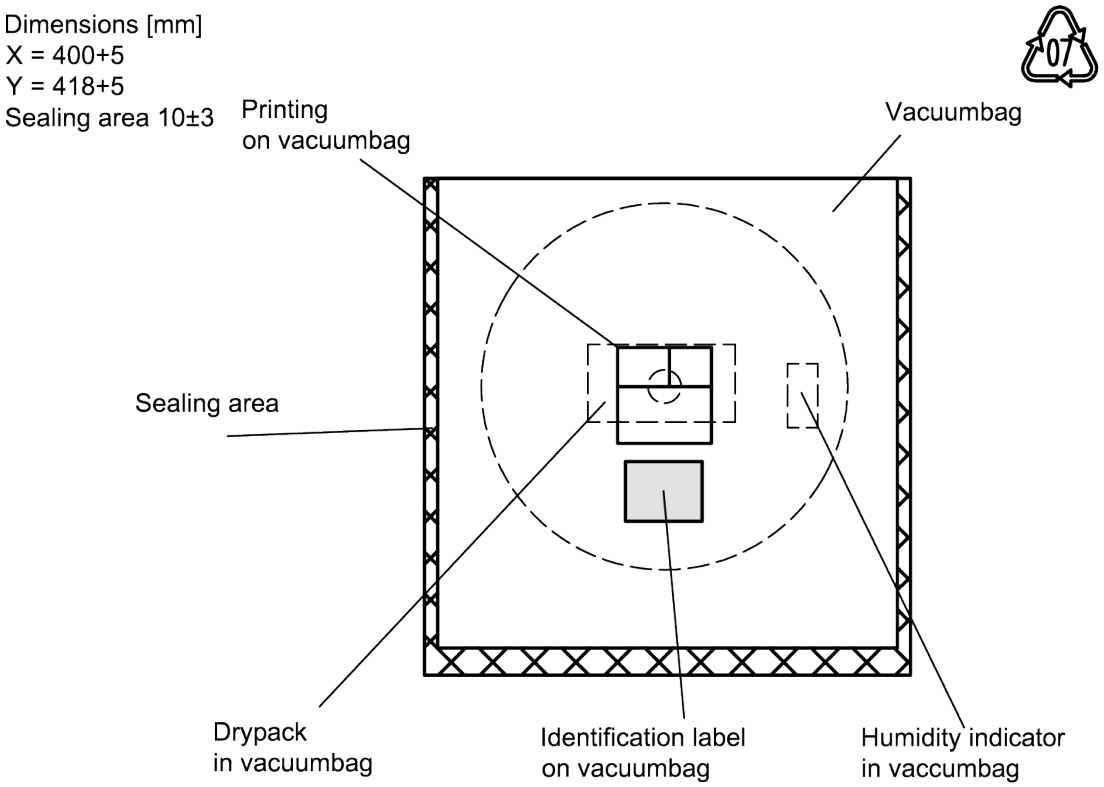

Figure 14: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

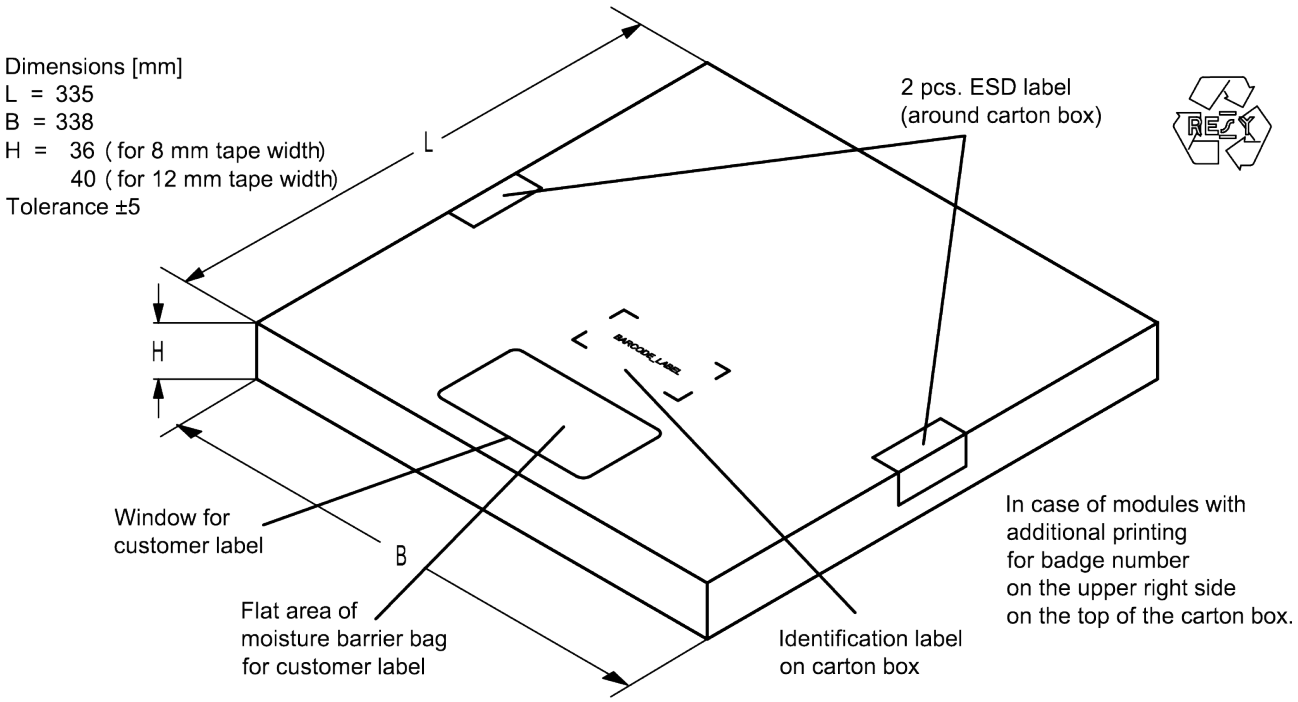

Figure 15: Drawing of folding box for reel with diameter of 330 mm.

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 2: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

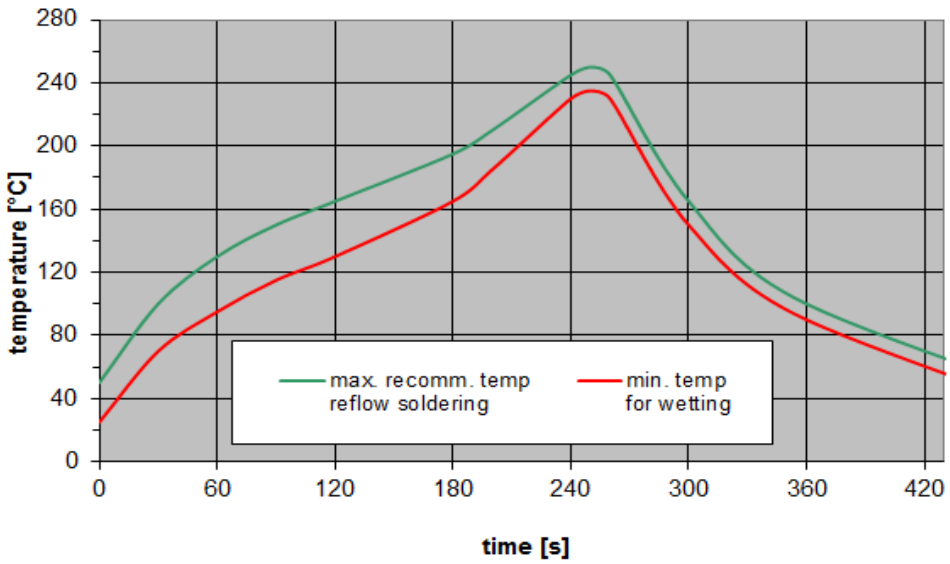

Figure 16: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 Annotations

13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14 Cautions and warnings

14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under https://rffe.qualcomm.com/.

14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

15 ESD protection of acoustic devices

Acoustic devices are **E**lectro **S**tatic **D**ischarge sensitive devices. To reduce the probability of damages caused by ESD, special matching topologies must be applied.

In general, “ESD matching” must be ensured at that electrical port, where electrostatic discharge is expected.

Electrostatic discharges predominantly appear at the antenna input of RF receivers. Therefore, only the input matching of the acoustic device must be designed to short circuit or to block the ESD pulse.

Below three figures show recommended “ESD matching” topologies.

For wide band acoustic devices the high-pass ESD matching structure needs to be at least of 3rd order to ensure a proper matching for any impedance value of antenna and input port. The required component values must be determined from case to case.

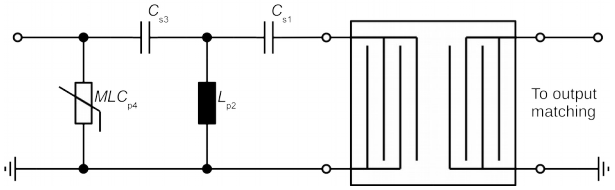

Figure 17: MLC varistor plus ESD matching.

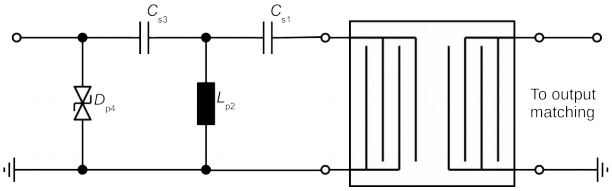

Figure 18: Suppressor diode plus ESD matching.

In cases where minor ESD occur, following simplified “ESD matching” topologies can be used alternatively.

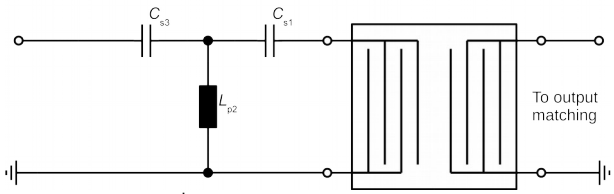

Figure 19: 3rd order high-pass structure for basic ESD protection.

In all three figures the shunt inductor L_{p2} could be replaced by a shorted microstrip with proper length and width. If this configuration is possible depends on the operating frequency and available PCB space.

Effectiveness of the applied ESD protection has to be checked according to relevant industry standards or customer specific requirements.

For further information, please refer to RF360 Application report: **“ESD protection for SAW filters”.** This report can be found under https://rffe.qualcomm.com.

16 Revision history

Changes compared to previously issued iteration.

Version	Detailed specification changes	Date
0.1	Design Goal.	Jan 14, 2021
0.2	Design Goal.	Feb 26, 2021
0.3	Design Goal.	Mar 01, 2021
1.0	TPV Sample Datasheet based AS83C-2 PCB.	Oct 12, 2021

17 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application.** As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified.** In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (https://rffe.qualcomm.com). Should you have any more detailed questions, please contact our sales offices.
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   The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.

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